

| Processing/Physical Characteristics | dry / cond | Unit | Test Standard |
|--|------------|------|-----------------|
| ISO Data | | | |
| ^[C] Molding shrinkage, parallel | 1.0 / * | % | ISO 294-4, 2577 |
| ^[C] Molding shrinkage, normal | 0.8 / * | % | ISO 294-4, 2577 |

[C]: CAMPUS

| Mechanical properties | dry / cond | Unit | Test Standard |
|--|-------------|-------------------|---------------|
| ISO Data | | | |
| ^[C] Tensile Modulus | 3700 / 1300 | MPa | ISO 527 |
| ^[C] Yield stress | 75 / - | MPa | ISO 527 |
| ^[C] Yield strain | 4 / - | % | ISO 527 |
| Flexural modulus, 23°C | 3200 / 1100 | MPa | ISO 178 |
| Flexural strength | 105 / 50 | MPa | ISO 178 |
| ^[C] Charpy impact strength, +23°C | 80 / - | kJ/m ² | ISO 179/1eU |
| ^[C] Charpy notched impact strength, +23°C | 4 / 14 | kJ/m ² | ISO 179/1eA |
| ^[C] Charpy notched impact strength, -30°C | 3.5 / - | kJ/m ² | ISO 179/1eA |

[C]: CAMPUS

| Thermal properties | dry / cond | Unit | Test Standard |
|---|------------|-------|-----------------|
| ISO Data | | | |
| ^[C] Melting temperature, 10°C/min | 257 / * | °C | ISO 11357-1/-3 |
| ^[C] Temp. of deflection under load, 1.80 MPa | 60 / * | °C | ISO 75-1/-2 |
| ^[C] Temp. of deflection under load, 0.45 MPa | 200 / * | °C | ISO 75-1/-2 |
| ^[C] Burning Behav. at 1.5 mm nom. thickn. | V-0 / * | class | IEC 60695-11-10 |
| Yellow Card available | yes / * | - | - |
| ^[C] Burning Behav. at thickness h | V-0 / * | class | IEC 60695-11-10 |
| Thickness tested | 0.8 / * | mm | - |

[C]: CAMPUS

| Electrical properties | dry / cond | Unit | Test Standard |
|---|------------|-------|---------------|
| ISO Data | | | |
| ^[C] Volume resistivity | 1E13 / - | Ohm*m | IEC 62631-3-1 |
| ^[C] Surface resistivity | * / 1E15 | Ohm | IEC 62631-3-2 |
| ^[C] Electric strength | 34 / - | kV/mm | IEC 60243-1 |
| ^[C] Comparative tracking index | 600 / - | - | IEC 60112 |

[C]: CAMPUS

| Other properties | dry / cond | Unit | Test Standard |
|------------------------|------------|-------------------|---------------|
| ^[C] Density | 1160 / - | kg/m ³ | ISO 1183 |

[C]: CAMPUS

Characteristics

Processing

Injection Molding

Applications

Electrical and Electronical

Special Characteristics

Flame retardant, Halogen-free